OSRAM KT DDLM31.13 Datasheet

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SYNIOS® S2222

KT DDLM31.13

This square package with just 2mm outline combines best performance with a small footprint. A centralized chip allows an easy integration in optical systems. The availability of different main colors and white points gives highest flexibility in various application areas.





Applications

- Access Control & Security
- Ambient Lighting
- Appliances & Tools
- Dynamic Signaling
- Entertainment
- Factory Automation
- Home & Building Automation

- Indoor Lighting
- Material Processing
- Projection & Display
- Robotics
- Static Signaling
- Transportation

Features

- Package: white SMT package, colorless clear silicone resin
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ_{dom} = 528 nm (• true green)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)



Ordering Information

Туре	Luminous Flux ¹⁾ I _F = 140 mA Φ_V	Ordering Code
KT DDLM31.13-6H7J-36-W4A4	31.5 63.0 lm	Q65112A5714



Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T _{op}	min.	-40 °C
	σp	max.	110 °C
Storage Temperature	T _{stg}	min.	-40 °C
	5	max.	110 °C
Junction Temperature	T _j	max.	125 °C
Junction Temperature for short time applications*	T _j	max.	150 °C
Forward current	I _F	min.	10 mA
T _s = 25 °C		max.	200 mA
Surge current t ≤ 10 µs; D = 0.005 ; T _s = 25 °C	Ι _{FS}	max.	400 mA
Reverse voltage ²⁾ T _s = 25 °C	V _R	max.	5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV

* The median lifetime (L70/B50) for Tj = 150° C is 100h.



Characteristics

 $I_{_{\rm F}}$ = 140 mA; $T_{_{\rm S}}$ = 25 °C

Parameter	Symbol	Values	
Dominant Wavelength ³⁾	λ_{dom}	min.	519 nm
I _F = 140 mA	uom	typ.	528 nm
		max.	543 nm
Viewing angle at 50% ${\rm I_v}$	2φ	typ.	120 °
Forward Voltage 4)	V _F	min.	2.60 V
$I_{\rm F} = 140 {\rm mA}$	I.	typ.	2.80 V
		max.	3.40 V
Reverse current ²⁾	I _B	typ.	0.01 µA
$V_{R} = 5 V$	K	max.	10 µA
Real thermal resistance junction/solderpoint ⁵⁾	$R_{thJS real}$	typ.	18 K / W
	this real	max.	22 K / W
Electrical thermal resistance junction/solderpoint ⁵⁾	R _{thJS elec.}	typ.	14 K / W
with efficiency η_e = 22 %	thus elec.	max.	17 K / W



Brightness Groups

Group	Luminous Flux ¹⁾ I _F = 140 mA min. Φ _V	Luminous Flux ¹⁾ I _F = 140 mA max. Φ _v	Luminous Intensity ⁶⁾ I _F = 140 mA typ. I _v
6H	31.5 lm	35.5 lm	11.1 cd
7H	35.5 lm	40.0 lm	12.5 cd
8H	40.0 lm	45.0 lm	14.0 cd
5J	45.0 lm	50.0 lm	15.7 cd
6J	50.0 lm	56.0 lm	17.5 cd
7J	56.0 lm	63.0 lm	19.6 cd

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ I _F = 140 mA min. V _F	Forward Voltage ⁴⁾ I _F = 140 mA max. V _F	
W4	2.60 V	2.80 V	
24	2.80 V	3.00 V	
64	3.00 V	3.20 V	
A4	3.20 V	3.40 V	

Wavelength Groups

Group	Dominant Wavelength ³⁾ $I_F = 140 \text{ mA}$ min. λ_{dom}	Dominant Wavelength ³⁾ I _F = 140 mA max. λ_{dom}	
3	519 nm	525 nm	
4	525 nm	531 nm	
5	531 nm	537 nm	
6	537 nm	543 nm	



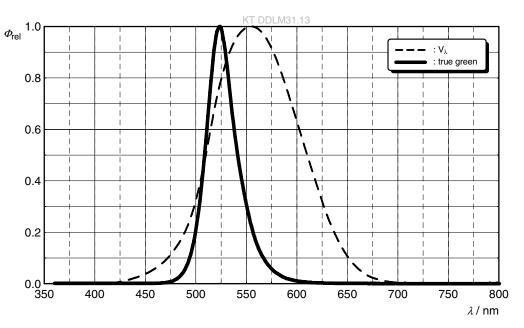
Group Name on Label

Example: 5J-3-24 Brightness	Wavelength	Forward Voltage	
5J	3	24	



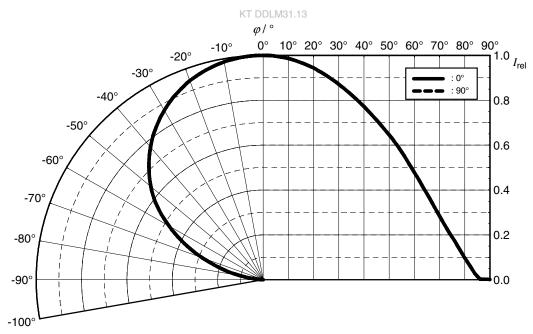
Relative Spectral Emission⁶⁾

 $\Phi_{_{rel}}$ = f (λ); I $_{_F}$ = 140 mA; T $_{_S}$ = 25 °C



Radiation Characteristics⁶⁾

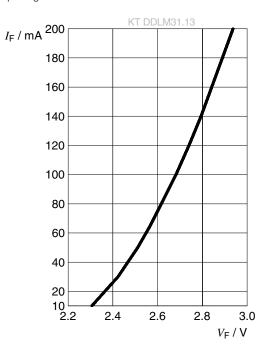
 $I_{rel} = f(\phi); T_s = 25 \ ^{\circ}C$





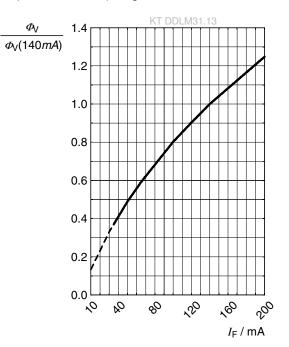
Forward current ⁶⁾

 $I_F = f(V_F); T_S = 25 \text{ °C}$



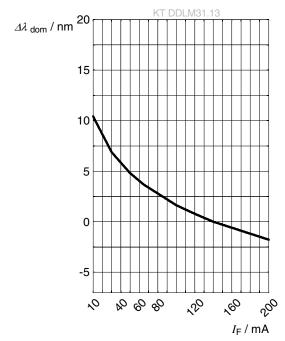
Relative Luminous Flux ^{6), 7)}

 $\Phi_{v}/\Phi_{v}(140 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$



Dominant Wavelength⁶⁾

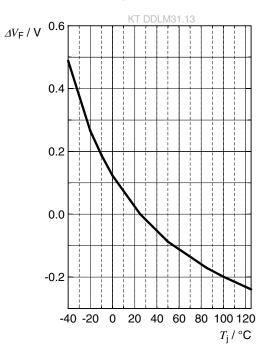
 $\Delta \lambda_{dom} = f(I_F); T_S = 25 \ ^{\circ}C$





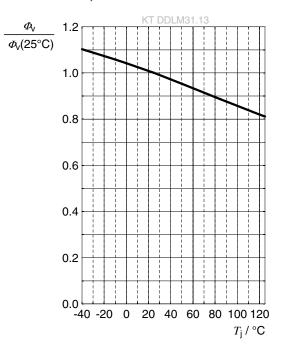
Forward Voltage ⁶⁾

 $\Delta V_{_F} = V_{_F} - V_{_F}(25 \text{ °C}) = f(T_{_J}); I_{_F} = 140 \text{ mA}$



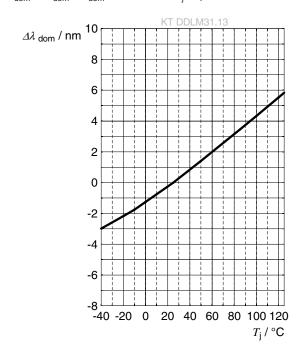
Relative Luminous Flux⁶⁾

 $\Phi_v/\Phi_v(25 \text{ °C}) = f(T_i); I_F = 140 \text{ mA}$



Dominant Wavelength ⁶⁾

 $\Delta \lambda_{dom} = \lambda_{dom} - \lambda_{dom} (25 \text{ °C}) = f(T_j); \text{ I}_{_{F}} = 140 \text{ mA}$





Max. Permissible Forward Current ⁵⁾

 $I_{F} = f(T)$

 $I_{\rm F}$ / mA 220

200

180 160

140 120

100 80

60

40

20

0

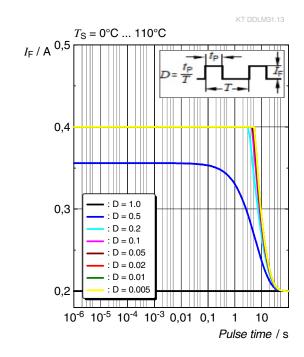
0

: T_s

20

Permissible Pulse Handling Capability

 $I_{_{P}} = f(t_{_{P}}); D: Duty cycle$



Permissible Pulse Handling Capability

40

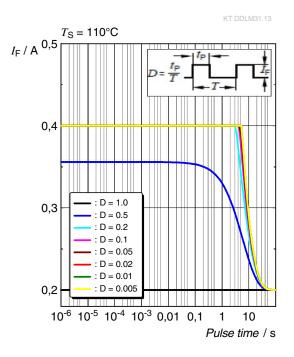
60

80

100

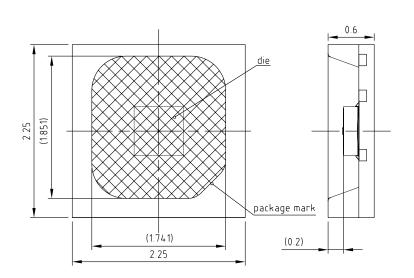
 $T_{s} / °C$

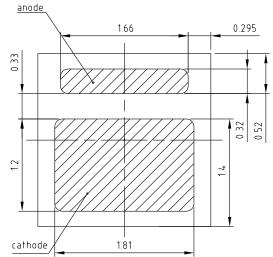
 $I_{F} = f(t_{p})$; D: Duty cycle





Dimensional Drawing ⁸⁾





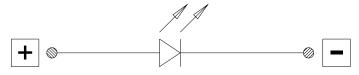
general tolerance ±0.1 lead finish Ag C67062-A0259-A2-06

Further Information:

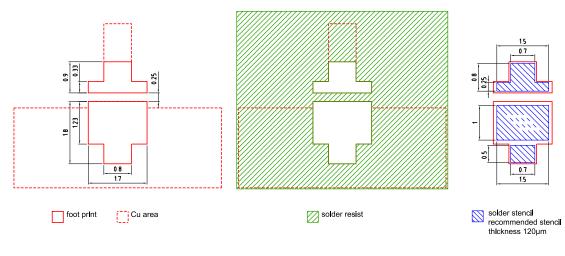
Approximate Weight: 6.0 mg



Electrical Internal Circuit



Recommended Solder Pad⁸⁾



board material selection has high impact on system reliability

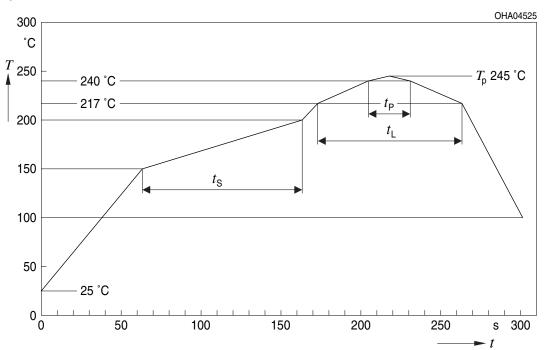
E062.3010.249 -01

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile





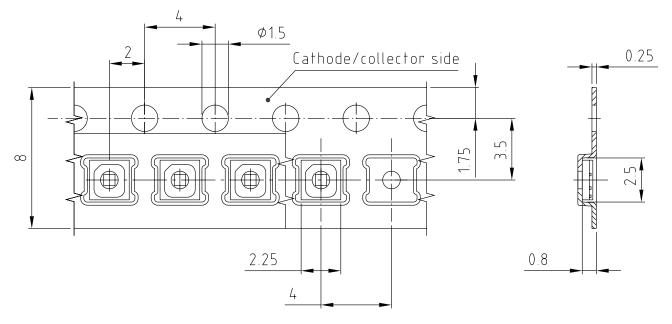
Profile Feature	Symbol	Pb	-Free (SnAgCu) Assembly		Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t _s T _{Smin} to T _{Smax}	t _s	60	100	120	S
Ramp-up rate to peak ^{*)} T_{smax} to T_{P}			2	3	K/s
Liquidus temperature	$T_{\scriptscriptstyle L}$		217		°C
Time above liquidus temperature	t		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T_{p} - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component

KT DDLM31.13 DATASHEET



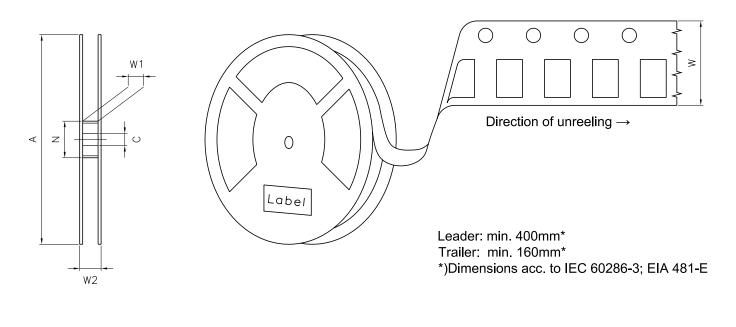
Taping⁸⁾



C67062-A0259-B8-09



Tape and Reel ⁹⁾

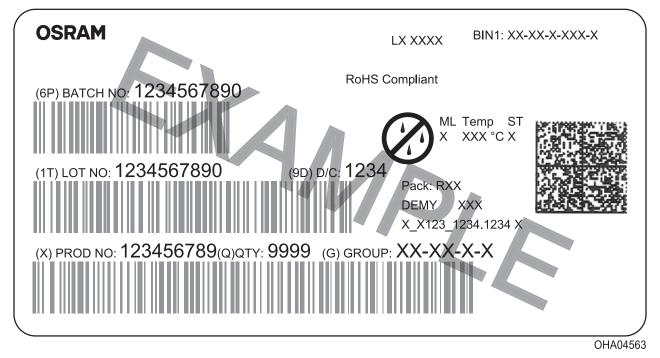


Reel Dimensions

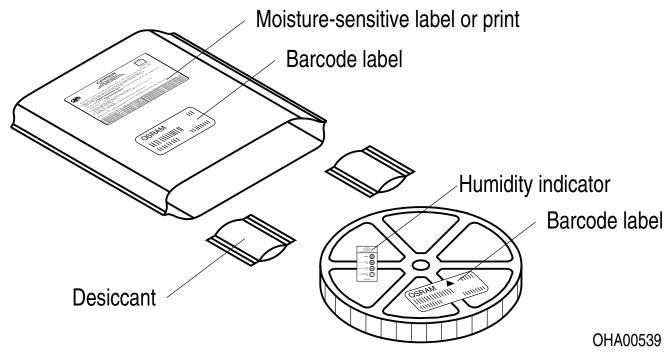
А	W	N _{min}	W ₁	$W_{2 \max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	4000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials⁸⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit https://ams-osram.com/support/application-notes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.



Glossary

- ¹⁾ **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 8 % and an expanded uncertainty of ± 11 % (acc. to GUM with a coverage factor of k = 3).
- ²⁾ Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- ³⁾ Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- ⁴⁾ **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ± 0.05 V and an expanded uncertainty of ± 0.1 V (acc. to GUM with a coverage factor of k = 3).
- ⁵⁾ **Thermal Resistance:** Rth max is based on statistic values (6σ) used for Derating.
- ⁶⁾ **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁷⁾ **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- ⁸⁾ **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁹⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



Revision History

Version	Date	Change
1.0	2019-12-15	Initial Version
1.1	2020-01-13	Brand
1.2	2020-04-24	Schematic Transportation Box Dimensions of Transportation Box
1.3	2020-07-17	Product Image Derating (Diagrams)
1.4	2023-10-19	New Layout Applications Notes



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

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